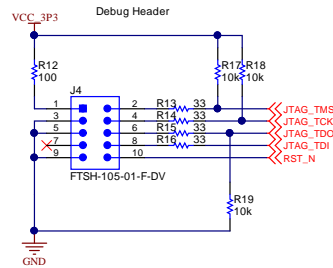
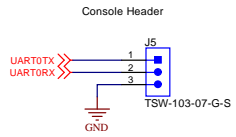
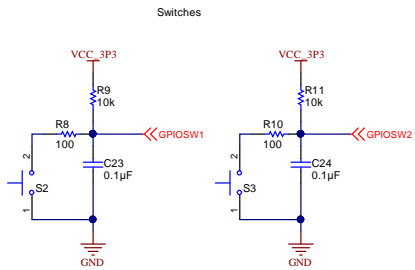
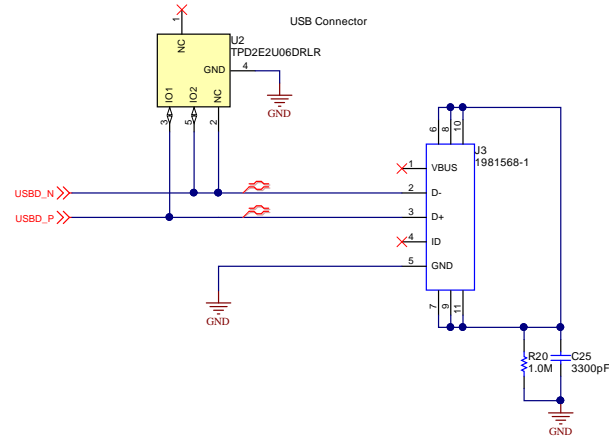


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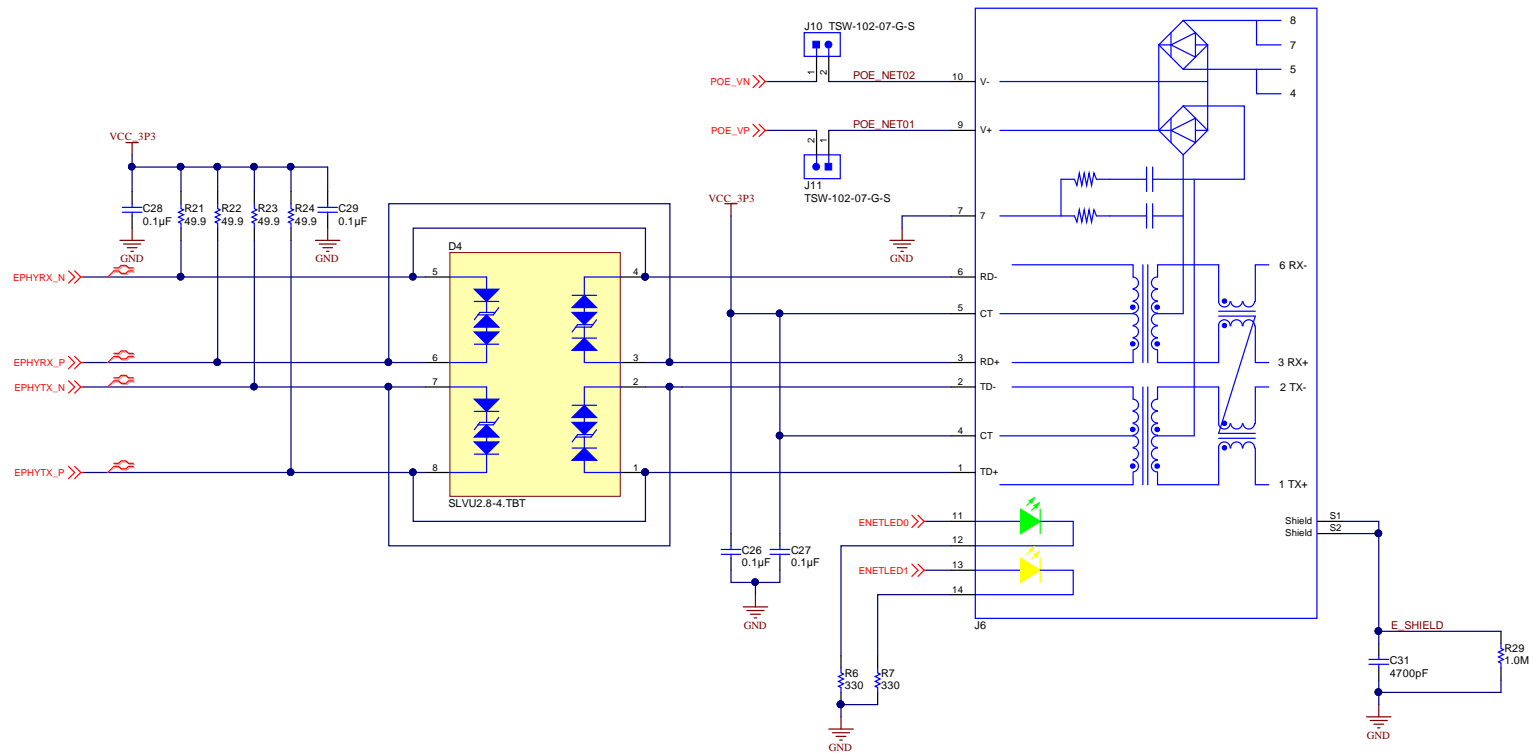


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TID #: TIDM-1018	Project Title: Power over Ethernet (PoE) for Connected IoT	
Number: TIDM-1018 Rev: A0	Sheet Title: Connector Schematics	
BYN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 2 of 4
Drawn By: Engineer: Amit Ashara	File: TIDM_1018_Connector_SchDoc	Size: B
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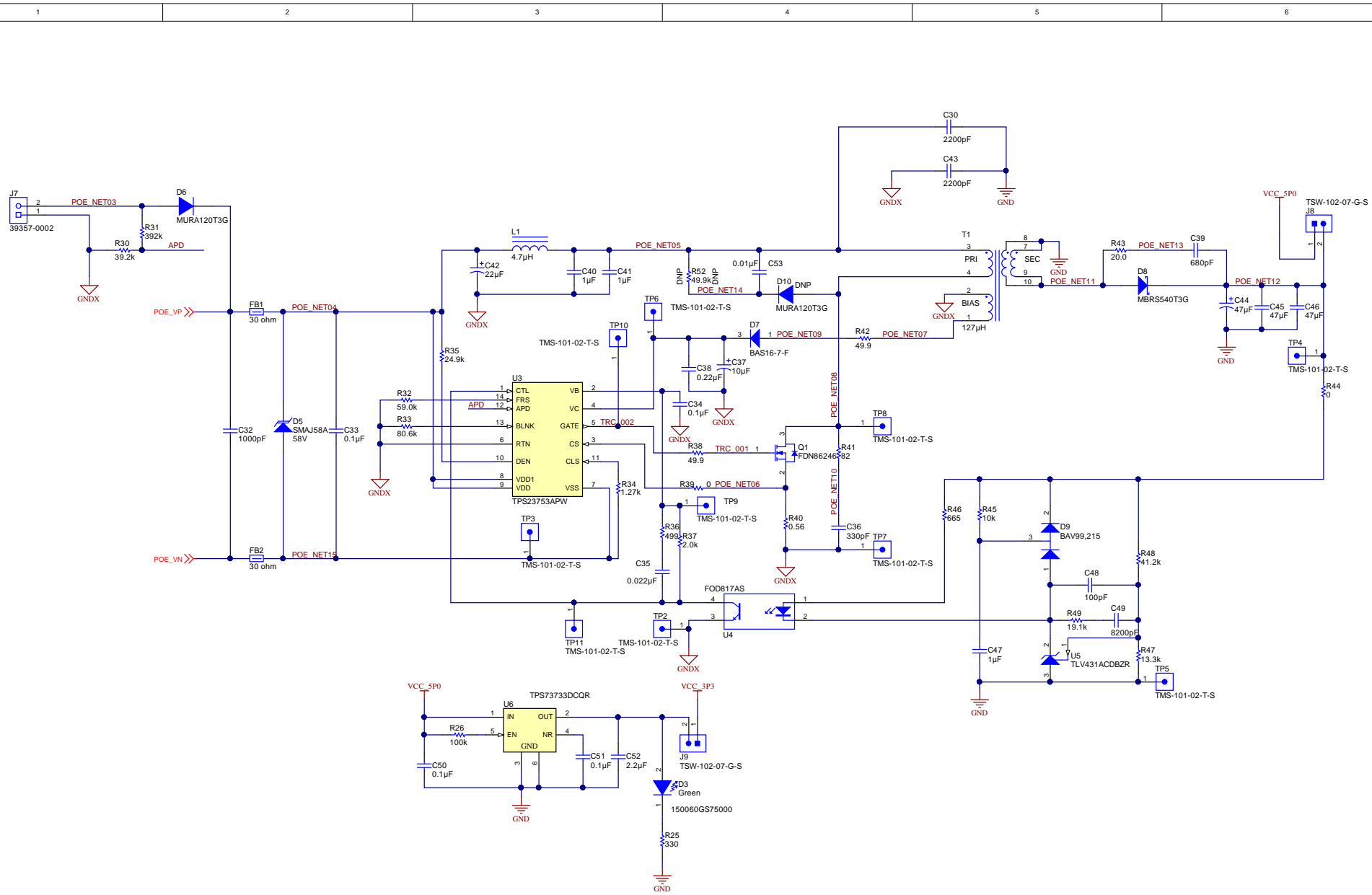


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Number: TIDM-1018	Rev: A0	Sheet Title: Ethernet Schematics
Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 3 of 4
Drawn By:	File: TIDM_1018_Ethernet_SchDoc	Size: B
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Number: TIDM-1018	Rev: A0	Sheet Title: Power Stage Schematics
BYN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 4 of 4
Drawn By:	File: TIDM_1018_PowerStage_SchDoc	Size: B
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